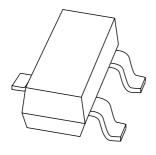
# **DISCRETE SEMICONDUCTORS**

# DATA SHEET



# PMBS3906 PNP general purpose transistor

Product data sheet Supersedes data of 1999 Apr 22 2004 Feb 02



# PNP general purpose transistor

**PMBS3906** 

#### **FEATURES**

• Low current (max. 100 mA)

• Low voltage (max. 40 V).

#### **APPLICATIONS**

• General purpose switching and amplification, e.g. telephony and professional communication equipment.

#### **DESCRIPTION**

PNP transistor in a SOT23 plastic package. NPN complement: PMBS3904.

#### **MARKING**

TYPE NUMBER	MARKING CODE(1)		
PMBS3906	*O6		

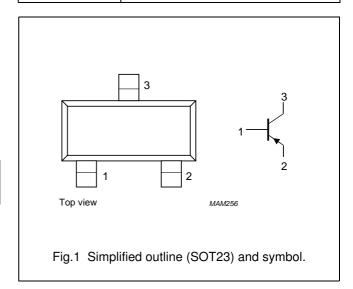
#### Note

1. \* = p : Made in Hong Kong.\* = t : Made in Malaysia.

\* = W : Made in China.

#### **PINNING**

PIN	DESCRIPTION
1	base
2	emitter
3	collector



#### **ORDERING INFORMATION**

TYPE		PACKAGE			
NUMBER	NAME	DESCRIPTION	VERSION		
PMBS3906	_	plastic surface mounted package; 3 leads	SOT23		

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	-40	٧
V <sub>CEO</sub>	collector-emitter voltage	open base	-	-40	٧
V <sub>EBO</sub>	emitter-base voltage	open collector	_	-5	٧
I <sub>C</sub>	collector current capability		-	-100	mA
I <sub>CM</sub>	peak collector current		_	-200	mA
I <sub>BM</sub>	peak base current		-	-200	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	-	250	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

# PNP general purpose transistor

PMBS3906

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	note 1	500	K/W

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

#### **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

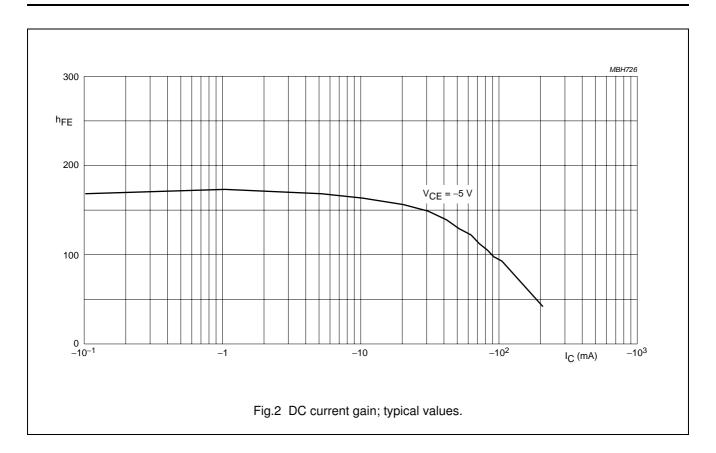
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	nA nA				
h <sub>FE</sub> DC current gain $ \begin{array}{c c} V_{CE} = -1 \ V; \ (see \ Fig.2) \\ I_{C} = -0.1 \ mA \\ I_{C} = -1 \ mA \\ \end{array} $	nA				
$I_{C} = -0.1 \text{ mA}$ $G_{C} = -0.1 \text{ mA}$					
$I_C = -1 \text{ mA}$ 80 $-$					
$I_{C} = -10 \text{ mA}$ 100 300					
$I_{C} = -50 \text{ mA}; \text{ note 1}$ 60 -					
$I_{C} = -100 \text{ mA}; \text{ note } 1$ 30 -					
$V_{CEsat}$ collector-emitter saturation voltage $I_{C} = -10$ mA; $I_{B} = -1$ mA $-250$	mV				
$I_{C} = -50 \text{ mA}; I_{B} = -5 \text{ mA}; \text{ note 1}$ - $-400$	mV				
$V_{BEsat}$ base-emitter saturation voltage $I_{C} = -10 \text{ mA}$ ; $I_{B} = -1 \text{ mA}$ $-850 \text{ m}$	mV				
$I_{C} = -50 \text{ mA}; I_{B} = -5 \text{ mA}; \text{ note 1} \qquad -950 \text{ mA};$	mV				
$I_E = i_e = 0; V_{CB} = -5 \text{ V}; f = 100 \text{ MHz}$ - 4.5	pF				
$I_C = i_C = 0$ ; $VE_B = -0.5 V$ ; $f = 100 MHz$ – 12	pF				
$I_{C} = -10 \text{ mA}; V_{CE} = -20 \text{ V};$ $I_{C} = 100 \text{ MHz}$ $I_{C} = -10 \text{ mA}; V_{CE} = -20 \text{ V};$ $I_{C} $	MHz				
F noise figure	dB				
Switching times (between 10% and 90% levels); (see Fig.3)					
$t_{on}$ turn-on time $I_{Con} = -10 \text{ mA}; I_{Bon} = -1 \text{ mA}; -100$	ns				
t <sub>d</sub> delay time I <sub>Boff</sub> = 1 mA - 50	ns				
t <sub>r</sub> rise time – 50	ns				
t <sub>off</sub> turn-off time – 700	ns				
t <sub>s</sub> storage time – 600	ns				
t <sub>f</sub> fall time – 100	ns				

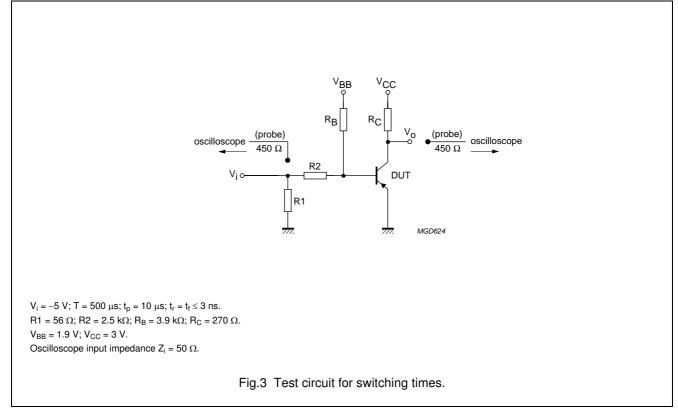
#### Note

1. Pulse test:  $t_p \le 300~\mu s;~\delta \le 0.02.$ 

# PNP general purpose transistor

# PMBS3906





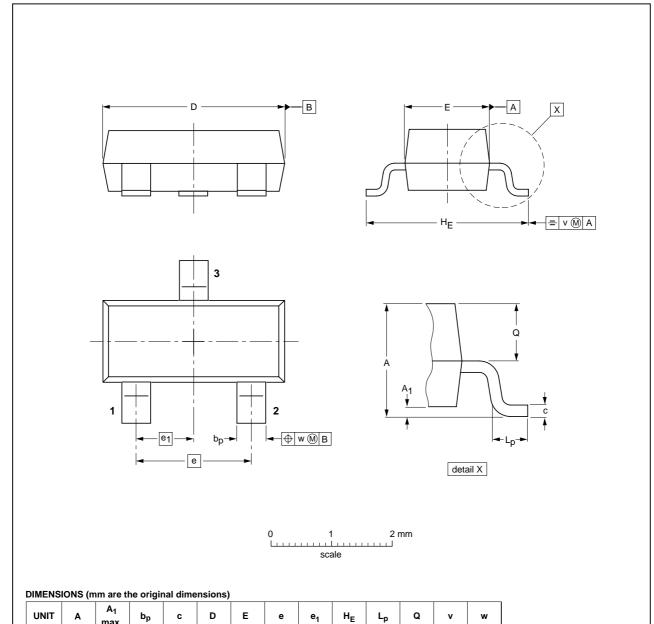
# PNP general purpose transistor

PMBS3906

#### **PACKAGE OUTLINE**

#### Plastic surface-mounted package; 3 leads

SOT23



OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT23		TO-236AB				<del>-04-11-04</del> 06-03-16

0.45

0.55

0.1

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max

0.38

0.9

### PNP general purpose transistor

PMBS3906

#### **DATA SHEET STATUS**

DOCUMENT STATUS(1)	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### **Notes**

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#### **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

#### **Contact information**

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